

Date: December 28, 2000

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231  
Box PATENT APPLICATION

Sir:

Transmitted herewith for filing is the patent  
application of:

Inventor: Lian, et al.

For: MULTI-LAYER Pt ELECTRODE FOR DRAM AND  
FRAM WITH HIGH K DIELECTRIC MATERIALS

This application includes:

16 pages: specification, claims and abstract  
6 sheets of drawings,    formal/ X informal  
   photographs

Also enclosed is:

   Declaration and Power of Attorney  
   Information Disclosure Statement pursuant to 37 CFR 1.56.

The filing fee has been calculated as shown below:

FOR:	(Col. 1) NO. FILED	(Col. 2) NO. EXTRA RATE	OTHER THAN A SMALL ENTITY FEE
BASIC FEE	XXXXXXXX	XXXXXXXXXX	XXXXX \$710
TOTAL CLAIMS	20 =	0	x 18= \$0
INDEP CLAIMS	3 =	0	x 80= \$0
* MULTIPLE DEPENDENT CLAIM PRESENTED			+260.= \$0
TOTAL			\$710

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